

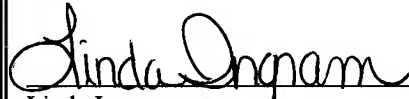
IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:	§	Attorney Docket No.
Hsien-Wei Chen, et al.	§	2003-1410 / 24061.193
	§	
Serial No.: 10/801,475	§	Customer No. 42717
	§	
Filed: March 16, 2004	§	Group Art Unit: 2822
	§	
For: SYSTEM FOR HEAT	§	Examiner: Monica Lewis
DISSIPATION IN	§	
SEMICONDUCTOR DEVICES	§	Confirmation No.: 1783

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

I hereby certify that this correspondence (including any listed enclosures) is being electronically filed in the United States Patent and Trademark Office via the EFS-Web system on June 29, 2007.


Linda Ingram

RESPONSE UNDER 37 C.F.R. §1.111

This Response is submitted in reply to the Office Action mailed on April 5, 2007. (Please see the pages that follow).